

Achilles Wafer Shipping Products



Wafer Shipping Product Introduction

Wafer shipping container

Protos Carrier NA series

NA-300LA (for 300mm wafer)



Features

- The wafer edge hold structure (Compression Tab) prevents breakage during transporting wafer.
- Can pack Wafer MAX 25 Pieces
- Improvement of Shipping efficiency
- Made from low-particle, low-ionic, conductive PP (Surface resistivity <1X10⁹Ω)
- Automatic wafer packing machine correspondence

Packaging Style



Achilles can provide improved protection & safety transportation system for valuable Semiconductor.



Wide Product Line-up

Wafer size	Horizontal Wafer Shipper	Film Frame Shipper	
4inch 100mm	MA-6S & Inner Tray VFS-4-6 For compound semiconductor		
6inch 150mm	MA-6S	ND-6	
8inch 200mm	MA-8S NA-8M	ND-8	
12inch 300mm	NA-12F NA-300LA	NDM-12 NDM-12M	



Achilles Horizontal Wafer Shipper

Features

- Safety of transporting
- II. Cost reduction of transportation
- III. Automated machine applicable
- IV. Cleanliness & ESD protection
- V. Wide product Line-up

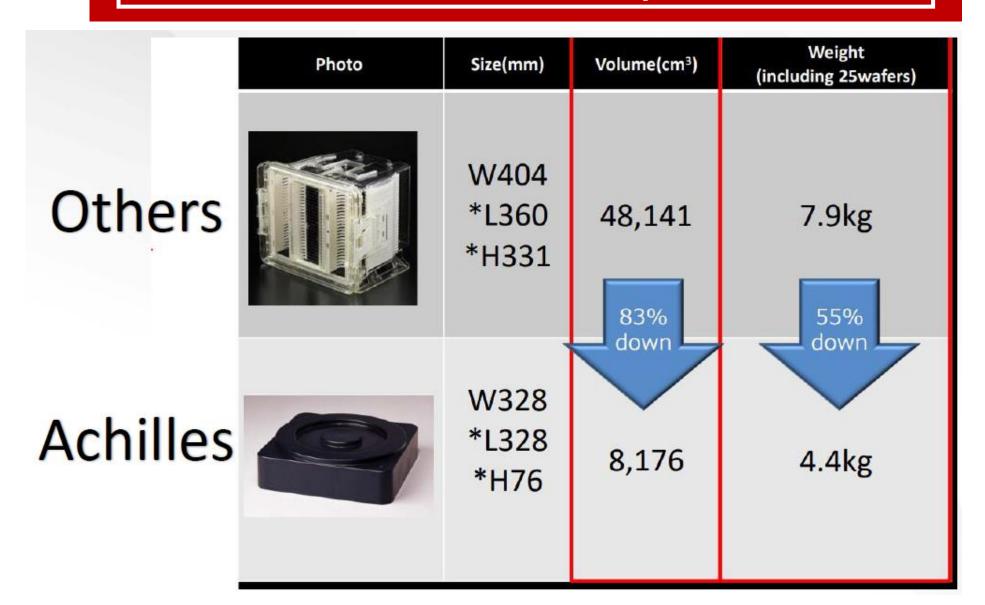


NA-8M for 8inch wafer



NA-300LA for 12inch wafer

Cost Reduction of Transportation

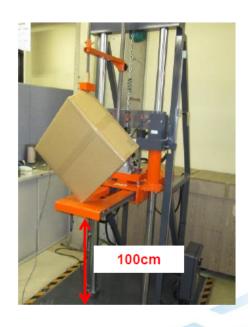


Transport Breakage Test

The wafer edge hold structure (Compression Tab) prevents breakage during transporting wafer.

*We dropped it from the height of 100 cm(Severe Level!!) to the concrete floor. based on evaluation method of ISO 2248:1985.

Drop Condition	Drop Direction	Shock Acceleration(G)	Result Wafer State
	1 Corner	34.5	No Crack
	2 Edge	51.6	No Crack
Drop Height: 100cm Free fall to concrete	3 Edge	44.6	No Crack
floor	4 Edge	44.8	No Crack
<iso 2248:1985=""></iso>	5 Side	50.1	No Crack
Wafer Thickness: 775µm	6 Side	51.2	No Crack
·	7 Side	51.1	No Crack
【G/W:4.7kg】 【N/W:5.7kg】	8 Side	52.0	No Crack
	9 Side(TOP)	89.2	No Crack
	10 Side(BTM)	75.8	No Crack



Achilles Horizontal Wafer Shipper

Features

- ESD protection
- II. High cleanliness (Low particle & Low ion contamination)
- III. Automated machine applicable, easy to separate from wafer
- IV. Contactless transportation by using the ring spacer



Anti-static type PEA (Z1)



Conductive type CPS (Z2)



Ring Spacer T-WSR



Achilles' unique compounding technology gives the interleaf the performance, low particles, and low ion contamination.

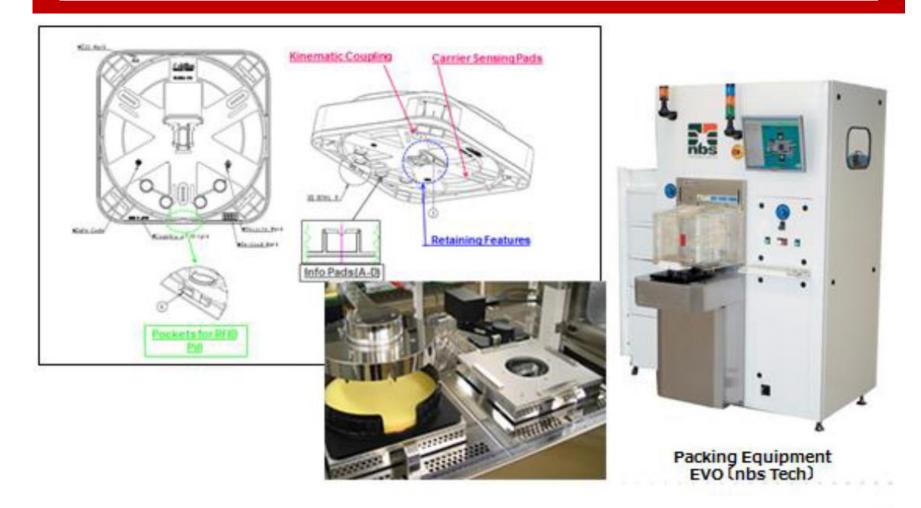
The professional technology service provider

Contactless Horizontal Wafer Shipper (for 12")

- No -contact on both side of the wafer surface by using ring spacer
- Enables safe transport and storage of wafers without the risk of contamination
- For transporting and storage of lens of bumped wafers
- Automated machine applicable



Automation Interface

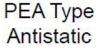


Wafer, interleaf and cushion in NA-300LA Horizontal Wafer Shipper easily handled by the automation tool.

Spacer

- 1. Lower particle counts
- 2. Less ion contamination
- 3. ESD controlled
- 4. Both faces same design
- Machine handling
- 6. Easy to separate from wafer







CPS Type Conductive

Protos Spacer PEA type

Product code; PEA- \square -350 (Z1) Material: Anti-static Polyethylene Electrical Resistance: < 1 \times 1 0 1 2 Ω

Thickness: 350µm

Protos Spacer CPS type

Product code: CPS-□-350 (Z2)

Material : Conductive Polyethylene Electrical Resistance : $< 1 \times 10^{8}\Omega$

Thickness: 350µm

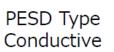


Cushion

- 1. Polyethylene cushion
- 2. Shock absorbing feature
- 3. Controlled low ion contamination
- 4. Ideal for protecting ultra thin wafers
- 5. Independent foaming structure for anti-dust protection

PEAS Type Antistatic







Protos Cushion PEAS type

Product code: MA-□PEAS-1/3/5/6/10

Material: Antistatic

Electrical resistance: $< 1 \times 10^{12} \Omega$

Thickness: 1/3/5/6/10 mm

Protos Cushion PESD type

Product code: MA-□PESD-1/3/5/10

Material: Conductive polyethylene foam

Electrical resistance: $1 \times 10^5 \Omega < R < 1 \times 10^9 \Omega$

Thickness: 1/3/5/10 mm

Conclusion

		Memory ···etc.	Logic ···etc.	Image Sensor, Glass ···etc.
HWS	MA Series	•	•	
	NA Series	•	•	•
Cushion	MA-□PEAS	•		•
	MA-□PESD		•	
Spacer	PEA-□	•		
	CPS-□		•	

- Achilles wafer package systems are used by many semiconductor manufactures around the world.
- We can provide all items for your wafer package (HWS System).
- We can provide many products of low particle, low ion contamination.
- We can propose various ESD counter measures by utilizing our many years of experience.

Add-on: Chip Tray Spacer

- 1. Lower particle counts
- 2. Less ion contamination
- 3. ESD controlled
- 4. Both faces same design
- 5. Machine handling
- 6. Easy to separate from wafer



Protecting Power devices from ESD

Protos Spacer CPS type

Product code: CPS-166 × 90-250

Material : Polyethylene + Carbon Black

Electrical Resistance : $<1 \times 10^9 \Omega$

Thickness: 250µm

Protos Spacer ST-PET type (Clear)

Product code: ST-PET88 × 88-100ANNAL

Material : PET + ST(Conductive Coating)

Electrical Resistance : $<1 \times 10^7 \Omega$

Thickness: 100µm



Add-on: Tray for Compound Wafer

- Safely transport and easily handle fragile 6" GaN/GaAs.
- 2. ESD controlled
- 3. Machine handling

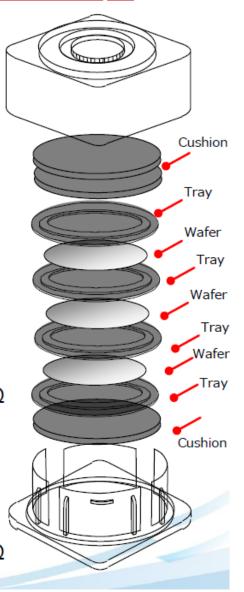


VFS Tray

Product code : VFS-6-8R-65A Material : A-PET+ST Coating Electrical Resistance : $<1 \times 10^7 \Omega$

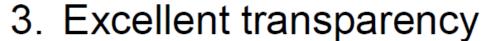
VFS(Black Tray)

Product code : VFS-6-8R-65B Material : A-PET+CB Coating Electrical Resistance : $<1 \times 10^7 \Omega$



Add-on: Antistatic Bag

- Moisture-proof without using Metal vapor deposition or foil
- 2. Antistatic coating treatment AS-TED Inner and outer coat AS-TED II Outer coat only



AS-TED II Bag

Product code: AS-TED2 180 × 300 Moisture Permeability <0.1[g/m² · 24h]

Material : Coat / PET / NY/ PE Electrical Resistance : $<1 \times 10^9 \Omega$

